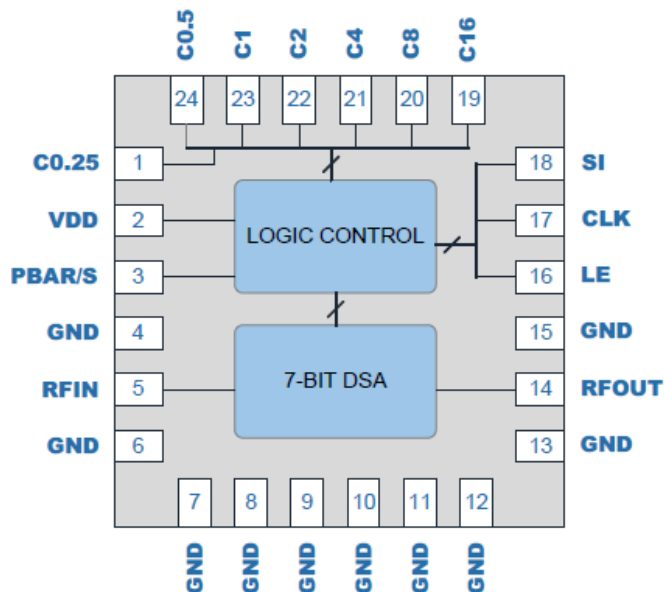# RFSA3714
50MHz to 6000MHz, Digital Step Attenuator

General Description

Qorvo's RFSA3714 is a 7-bit digital step attenuator (DSA) that features high linearity over the entire 31.75dB gain control range with 0.25dB steps. The RFSA3714 features three modes of control: serial, latched parallel, and direct parallel programming. The RFSA3714 has a low insertion loss of 1.5dB at 2GHz. Patent pending circuit architecture provides Overshoot-free transient switching performance. The RFSA3714 is available in a 4mm x 4mm QFN package.

24 Pad 4.0mm x 4.0mm x 0.85mm QFN Package

Product Features

- 7-Bit, 31.75dB Range, 0.25dB Step
- Patented Circuit Architecture
- Overshoot-free Transient of DSA Settings
- Frequency Range 50MHz to 6000MHz
- High Linearity, IIP3 +55dBm Typical
- Serial and Parallel Control Interface
- Switching Time 120nsec Typical
- Single Supply 3V to 5V Operation
- No DC Voltage on RF Pins, External DC Grounding Allowed
- Power-up Default Maximum Attenuation

Functional Block Diagram

Top View

Applications

- 2G through 4G Base Stations
- Point-to-Point
- WiFi
- Test Equipment

Ordering Information

Part No.	Description
RFSA3714TR13	13" Reel with 2500 pieces
RFSA3714PCK-410	50MHz to 6000MHz Evaluation Board with 5-piece sample bag

Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	−40 to +150 °C
RF Input Power at RFIN, T=105 °C	+30 dBm
RF Input Power at RFOUT, T=105 °C	+27 dBm
Supply Voltage (V_{DD})	-0.5V to +6 V
All Other DC and Logic Pins [1][2]	-0.5V to +6 V

Notes:
1. Supply Voltage Must Be Applied Prior to Any Other Pin Voltages.
2. Not to exceed V_{DD}.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

Recommended Operating Conditions

Parameter	Min	Typ	Max	Units
Temperature Range [1]	-40		+105	°C
Junction Temperature			+125	°C
Supply Voltage (V_{DD})	+2.7		+5.5	V

Notes:
1. RF Input Power Handling Derates Above 105°C

Electrical Specifications

Parameter	Conditions [1]	Min	Typ	Max	Units
General Performance					
Supply Current	Steady state operation, current draw during attenuation state transitions is higher.		180		µA
Thermal Resistance	At maximum attenuation state with RF power applied to the RFIN pin		55		°C/W
RF Input Power at RFIN Pin	Continuous operation at +105°C case temperature			+27	dBm
RF Input Power at RFOUT Pin	Continuous operation at +105°C case temperature			+20	dBm
RF Performance					
Frequency Range		50		6000	MHz
Insertion Loss	2000MHz, 0dB attenuation setting		1.5		dB
Attenuation Range	0.25dB step size		31.75		dB
Absolute Attenuation Error	50 MHz to 2.7 GHz		±(0.15 + 2 %)		dB
	2.7 GHz to 4 GHz		±(0.15 + 3 %)		dB
	4 GHz to 6 GHz		±(0.25 + 5 %)		dB
Input IP3			+55		dBm
Input P0.1dB			+30		dBm
Return Loss			15		dB
Input and Output Impedance			50		Ω
General Performance					
Switching Time	50% control to 10%/90% RF		120		nsec
Successive Step Phase Delta	2000MHz		2		Deg
Control					
Digital Logic Low		0		0.63	V
Digital Logic High		1.17		V_{DD}	V

Notes:
1. Typical performance at these conditions: Temp = 25°C, 2000MHz, 5V Supply Voltage
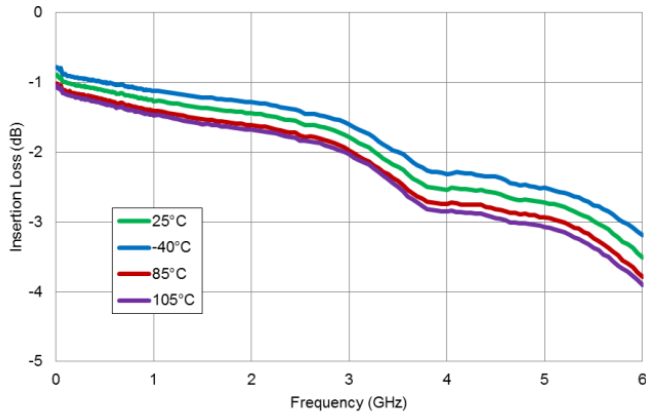
Typical Application Schematic
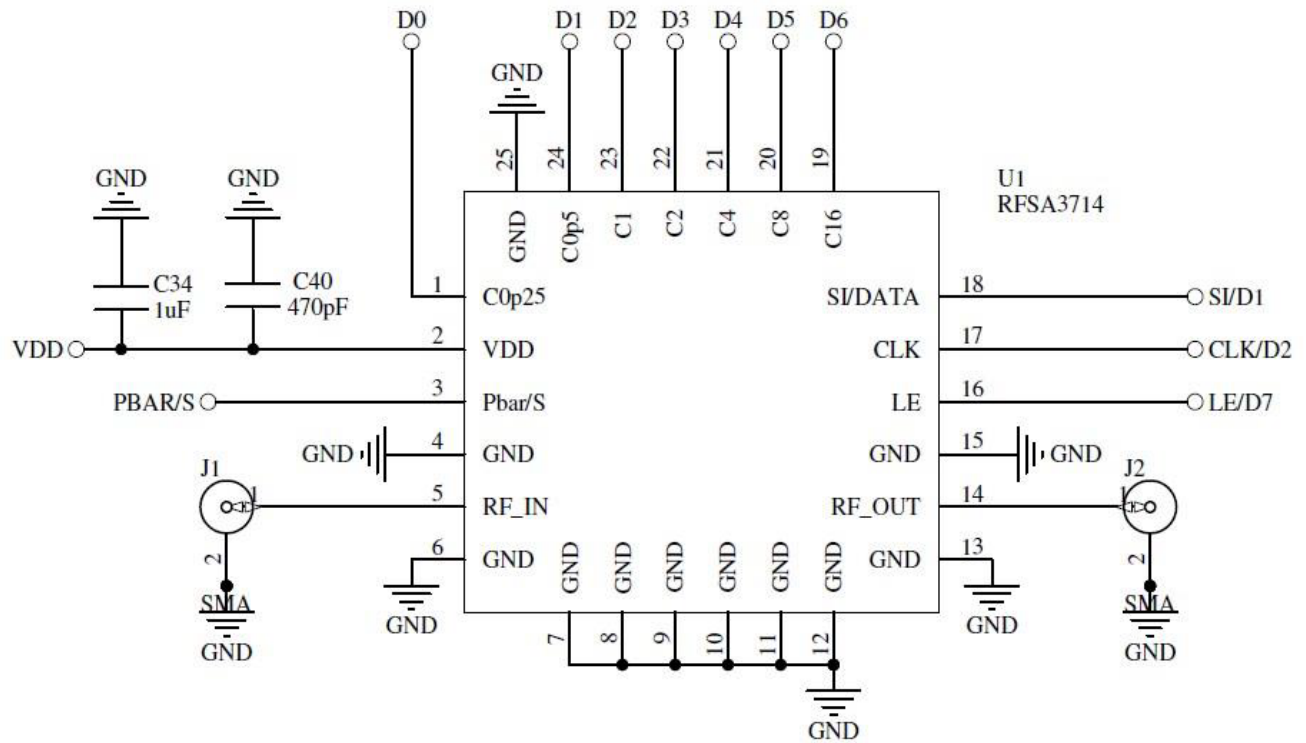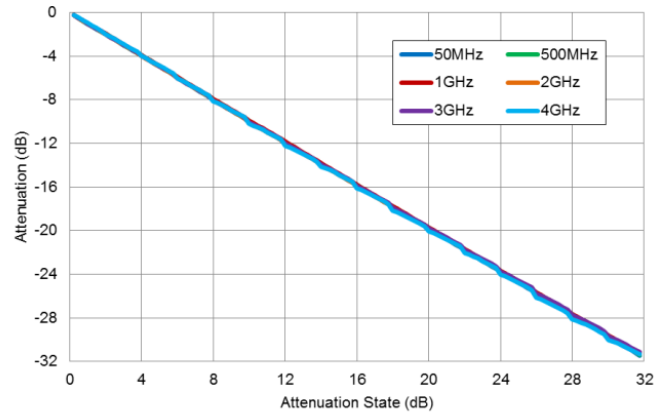
Performance Plots

Typical Performance: 0.25dB Steps
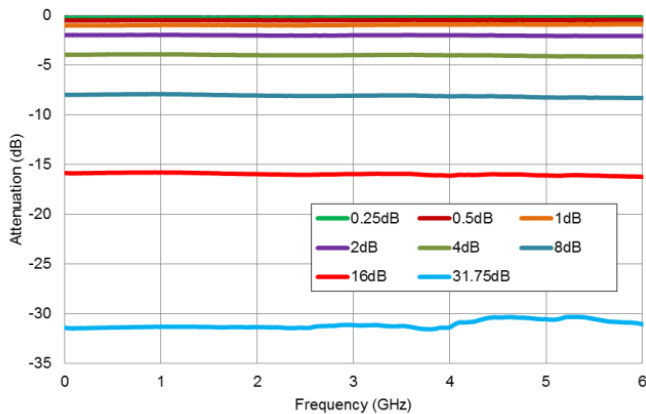
Minimum Insertion Loss versus Frequency
V_{DD} = 5V

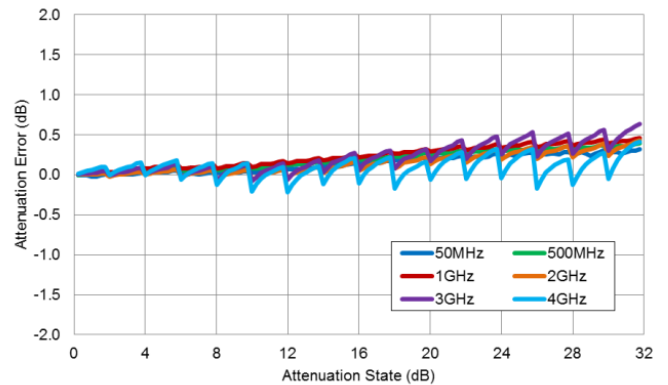**Normalized Attenuation versus Frequency**
V_{DD} = 5V, Temp = +25°C

Normalized Attenuation versus Frequency
V_{DD} = 5V, Temp = +25°C
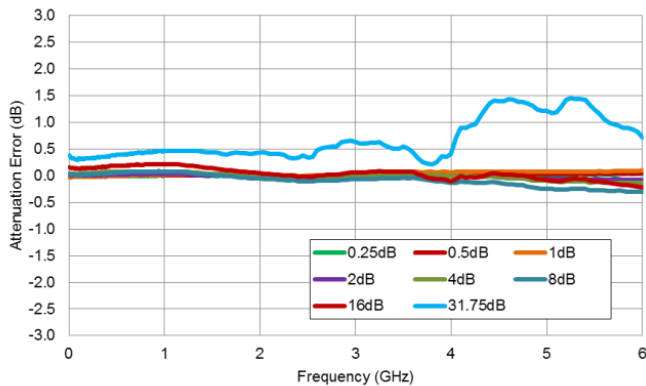
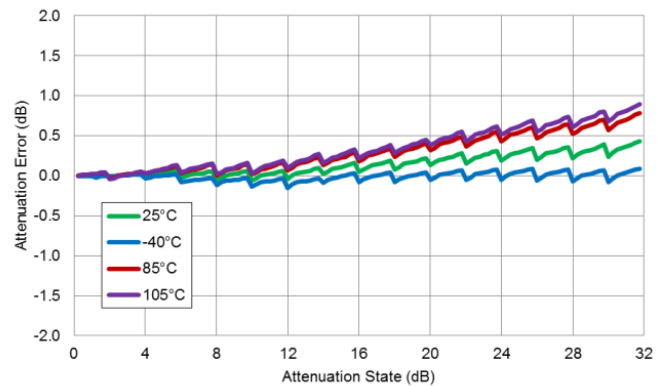**Absolute Attenuation Error versus Attenuation State**
V_{DD} = 5V, Temp = +25°C

Major State Absolute Attenuation Error versus Frequency
V_{DD} = 5V, Temp = +25°C
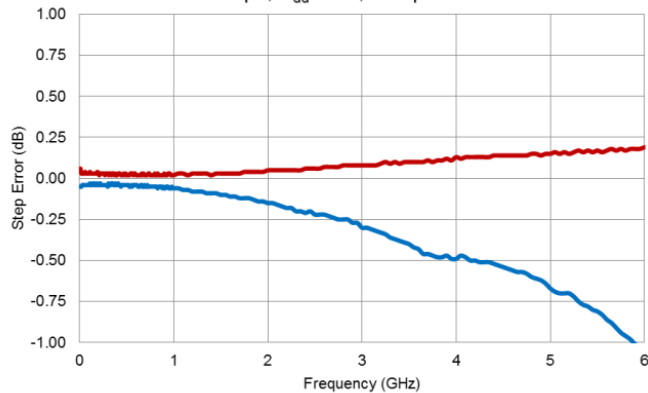
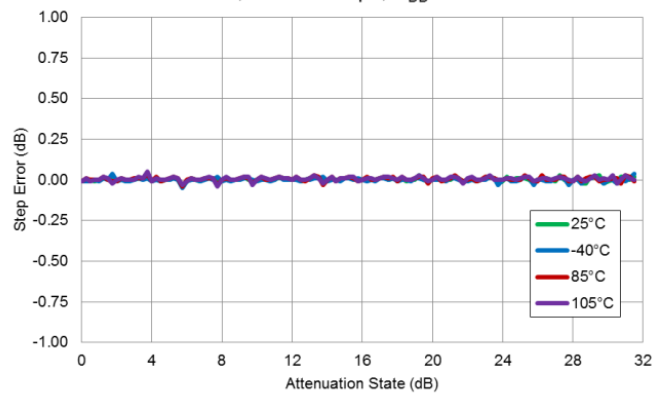**Absolute Attenuation Error versus Attenuation State**
2GHz, V_{DD} = 5V
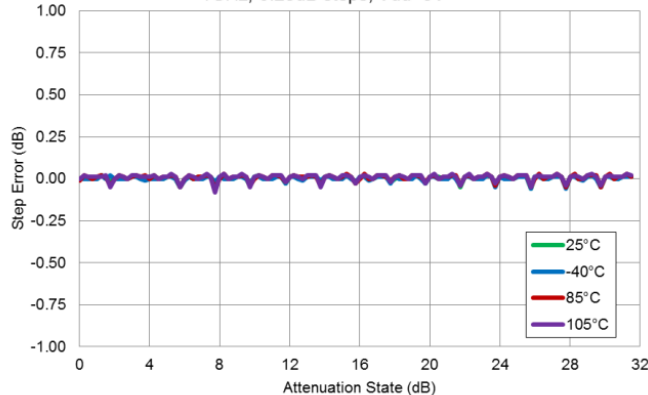
Performance Plots

Typical Performance: 0.25dB Steps

Worst Case Successive Step Error versus Frequency
0.25dB Steps, V_{dd} = 5V, Temp = +25°C

Successive Step Error versus Attenuation State
50MHz, 0.25dB Steps, V_{DD} = 5V

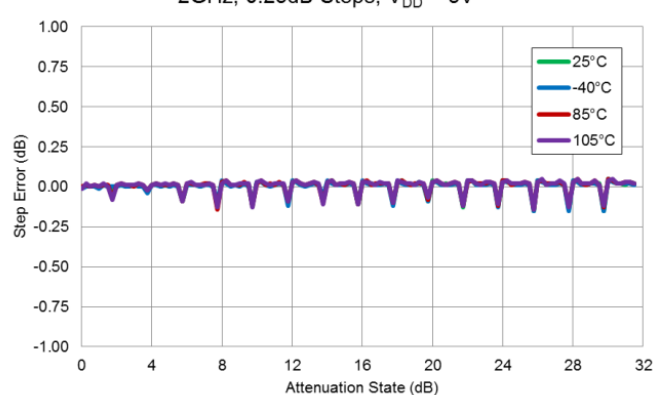**Successive Step Error versus Attenuation State**
1GHz, 0.25dB steps, Vdd=5V

Successive Step Error versus Attenuation State
2GHz, 0.25dB Steps, V_{DD} = 5V
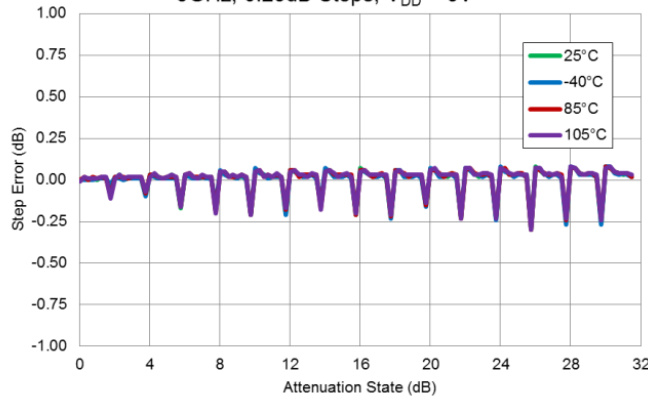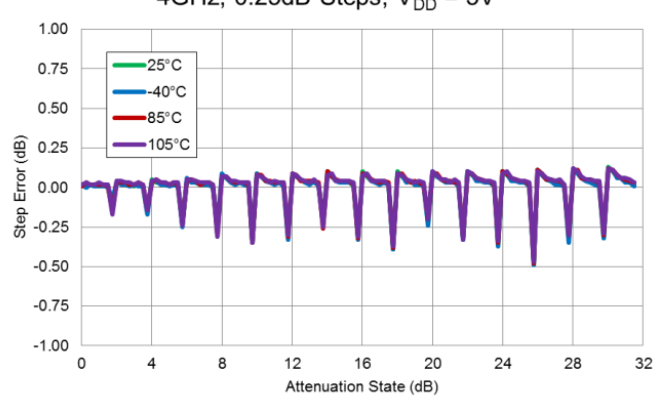
Successive Step Error versus Attenuation State
3GHz, 0.25dB Steps, V_{DD} = 5V

Successive Step Error versus Attenuation State
4GHz, 0.25dB Steps, V_{DD} = 5V

Performance Plots

Typical Performance: 0.25dB Steps

Input Return Loss versus Frequency
V_{DD} = 5V, Temp = +25°C

Output Return Loss versus Frequency
V_{DD} = 5V, Temp = +25°C

Input IP3 versus Frequency
V_{DD} = 5V, Pin = +18dBm/Tone, Temp = +25°C

Input IP3 versus Attenuation State
V_{DD} = 5V, Pin = +18dBm/Tone, Temp = +25°C

Input IP3 versus Attenuation State
RF 2GHz, V_{DD} = 5V, Pin = +18dBm/Tone

Supply Current versus Attenuation State
RF 2GHz, V_{DD} = 5V

Performance Plots

Typical Performance: 0.25dB Steps

Relative Phase versus Frequency
V_{DD} = 5V, Temp = +25°C

Relative Phase versus Attenuation State
V_{DD} = 5V, Temp = +25°C

Successive Step Phase Delta versus Attenuation State
50MHz, 0.25dB Steps, V_{DD} = 5V

Successive Step Phase Delta versus Attenuation State
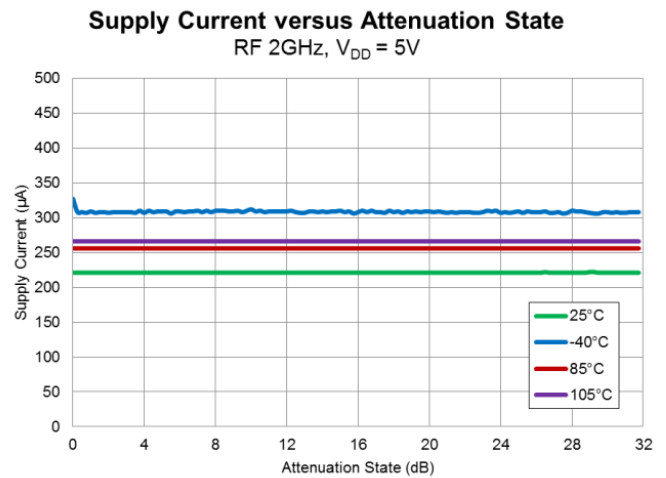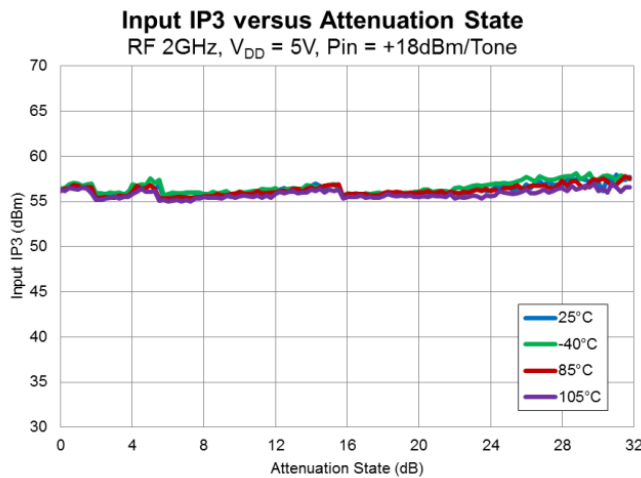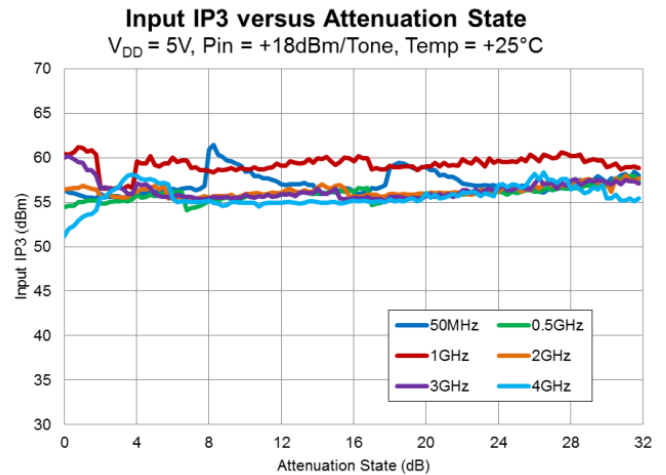4GHz, 0.25dB Steps, V_{DD} = 5V

Worst Case Successive Step Phase Delta versus Frequency
0.25dB Steps, V_{DD} = 5V, Temp = +25°C

Performance Plots

Typical Performance: 0.25dB Steps

Worst Case Successive Step Error versus Frequency
0.5dB Steps, V_{DD} = 5V, Temp = +25°C

Worst Case Successive Step Phase Delta versus Frequency
0.5dB Steps, V_{DD} = 5V, Temp = +25°C

Typical Performance: 1.0dB Steps

Worst Case Successive Step Error versus Frequency
1dB Steps, V_{DD} = 5V, Temp = +25°C
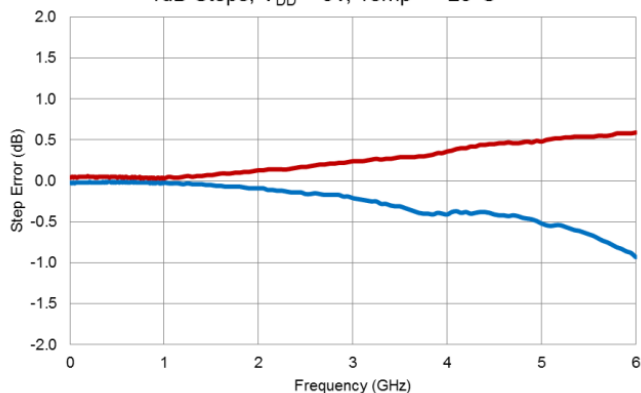
Worst Case Successive Step Phase Delta versus Frequency
1dB Steps, V_{DD} = 5V, Temp = +25°C
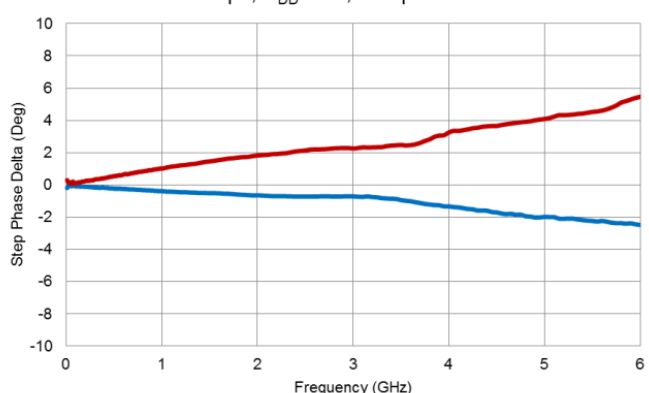
Notes:
1. Top 2 Plots: Attenuator remains monotonic if step error is less than +0.5dB.
2. Bottom 2 Plots: Attenuator remains monotonic if step error is less than +1.0dB.

Evaluation Board Schematic, 50MHz to 6000MHz Application
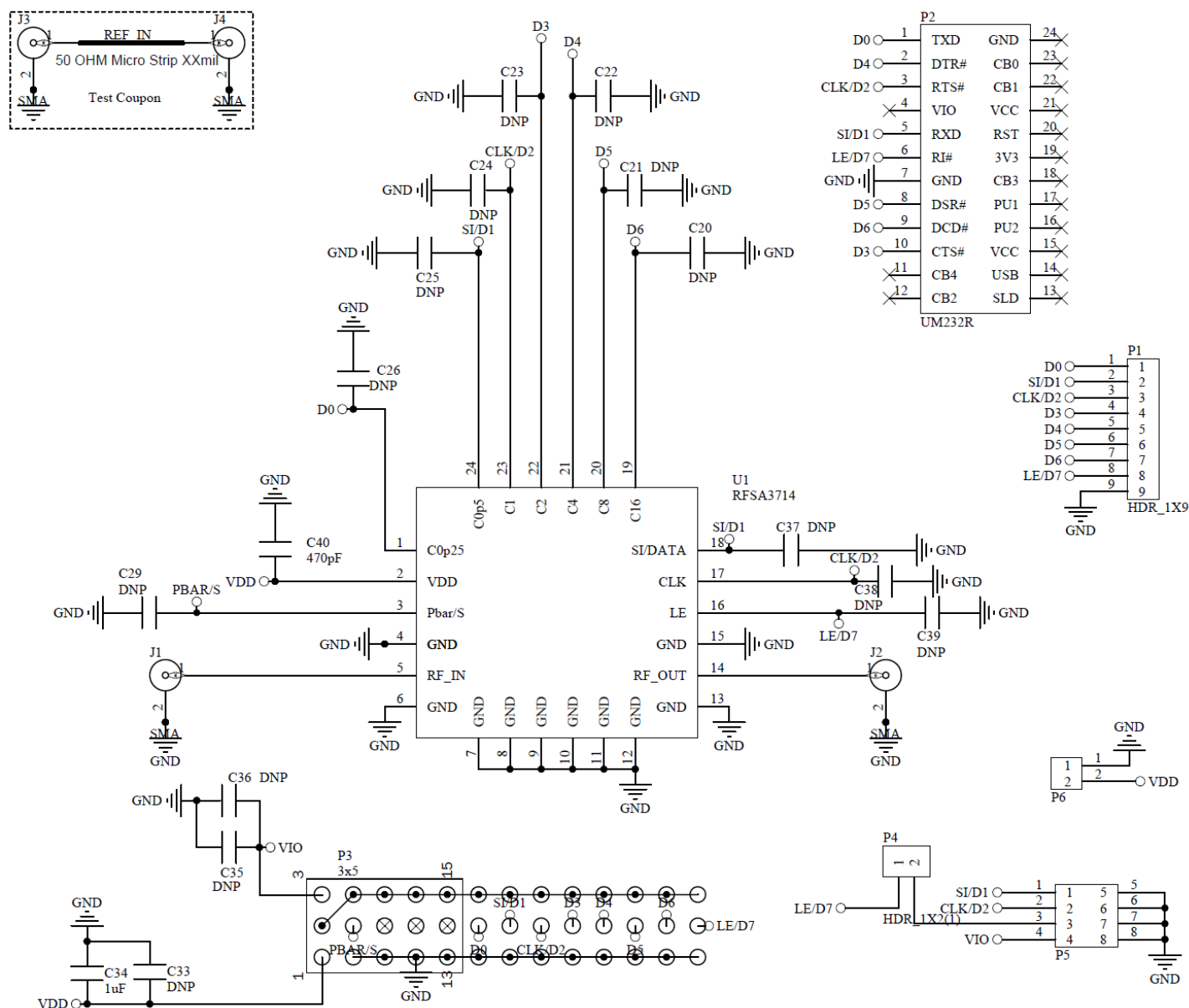
Evaluation Board Bill of Materials, 50MHz to 6000MHz Application

Reference Des.	Value	Description	Manuf.	Part Number
		SA3714-410	Dynamic Details (DDI) Toronto	SA3714-410(B)
U1		Digital Step Attenuator 50MHz to 6000MHz	Qorvo	RFSA3714SB
C34	1µF	CAP, 10%, 25V, X7R, 1206	Taiyo Yuden (USA), Inc.	CE TMK316BJ105KL-T
J1 – J4		CONN, SMA, END LNCH, UNIV, HYB MNT	Molex	SD-7351-4000
P1		CONN, HDR, ST, 9-PIN, 0.100"	Samtec Inc.	TSW-109-07-G-S
P2		CONN, SKT, 24-PIN DIP, 0.600", T/H	Aries Electronics Inc.	24-6518-10
M1 [1]		MOD, USB TO SERIAL UART, SSOP-28	Future Technology Devices	UM232R
P3 [2]		CONN, HDR, ST, 3 x 5, 0.100", T/H	Samtec Inc.	TSW-105-07-L-T
P4		CONN, HDR, ST, 2-PIN, 0.100:	Samtec Inc.	TSW-102-07-G-S
P5		CONN, HDR, 2 x 4, RA, 0.100, T/H	Samtec Inc.	TSW-104-08-G-D-RA
P6		CONN, HDR, ST, PLRZD, 2-PIN, 0.100"	ITW Pancon	MPSS100-2-C
C40	470pF	CAP, 5%, 50V, C0G, 0402	Murata Electronics	GRM1555C1H471JA01D
S1, S2[2]		Jumper, 2-Pin	3M Interconnect Solutions	929950-00
C20 – C26, C29, C33, C35 – C39, S6		DNP		

Notes:
1. M1 should be mounted into P2 with respect to the Pin 1 alignment of M1 and P2.
2. Jumpers S1 and S2 should be installed on P3.

Application for Enhanced Return Loss from 4 GHz to 6 GHz

The small signal frequency response of the RFSA3714 is improved to 6GHz by added a small tuning circuit to both the input and output side of the DSA on the existing evaluation board.

RFSA3714−PCB Evaluation Board with Additional Tuning Capacitors
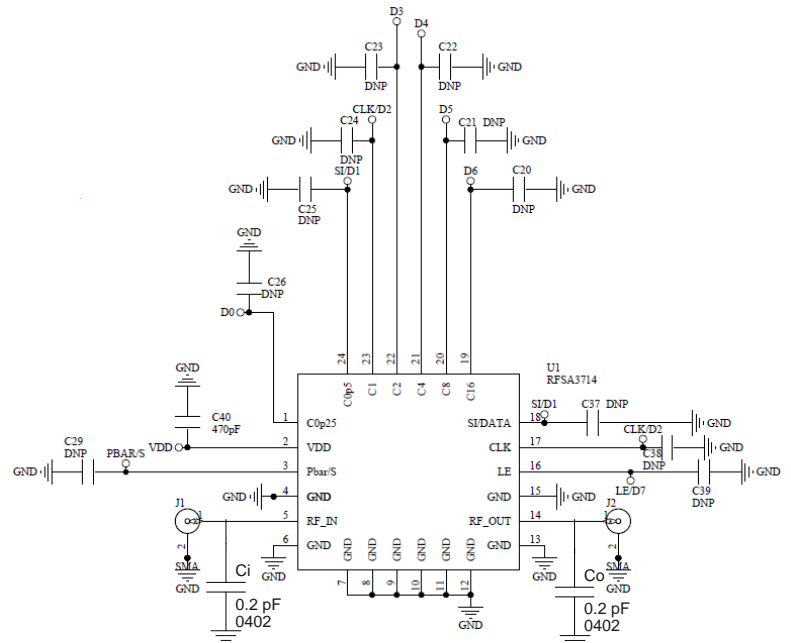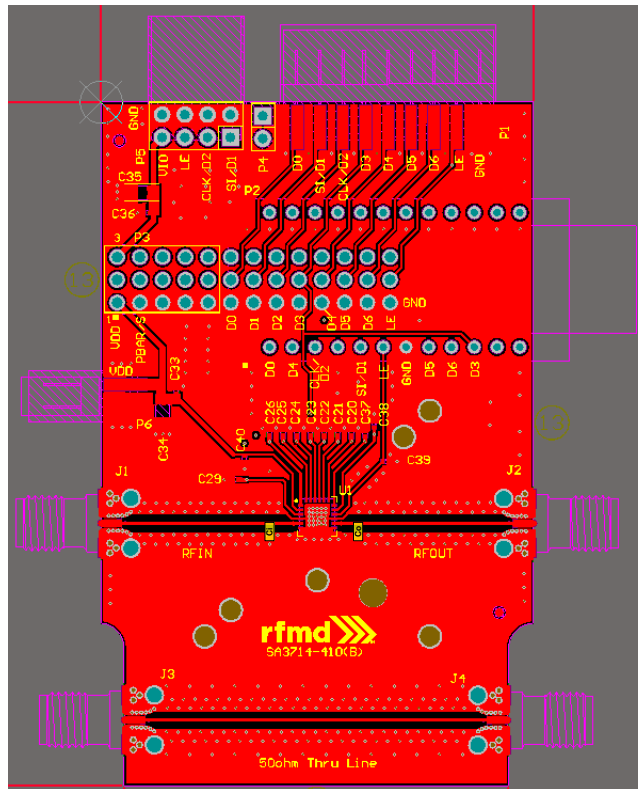
Notes:
1. Distance from Ci right edge to U1 left edge: 95 mils.
2. Distance from Co left edge to U1 right edge: 40 mils.

Performance Plots – Enhanced Return Loss from 4 GHz to 6 GHz

Test conditions unless otherwise noted: V_{DD} = +5.0V, Temp.= +25 °C

Input Return Loss vs. Frequency

Temp.=+25°C

Legend: 0dB, 0.25dB, 0.5dB, 1dB, 2dB, 4dB, 8dB, 16dB, 31.75dB

|S11| (dB) vs. Frequency (MHz)

Output Return Loss vs. Frequency

Temp.=+25°C

Legend: 0dB, 0.25dB, 0.5dB, 1dB, 2dB, 4dB, 8dB, 16dB, 31.75dB

|S22| (dB) vs. Frequency (MHz)

Gain vs. Frequency

Legend: 0dB, 0.25dB, 0.5dB, 1dB, 2dB, 4dB, 8dB, 16dB, 31.75dB

Temp.=+25°C

Gain (dB) vs. Frequency (MHz)
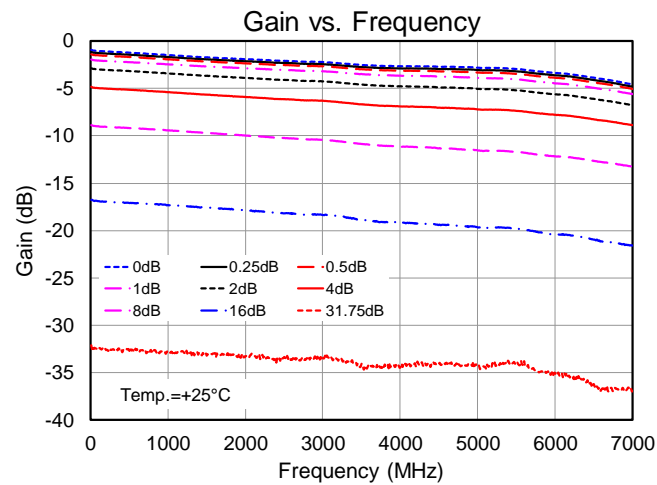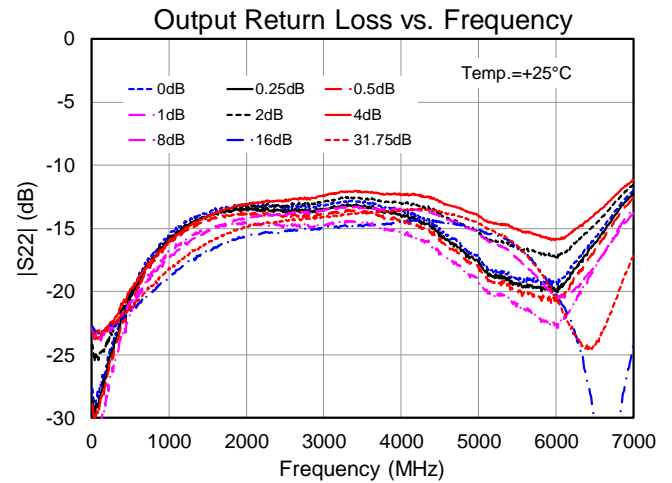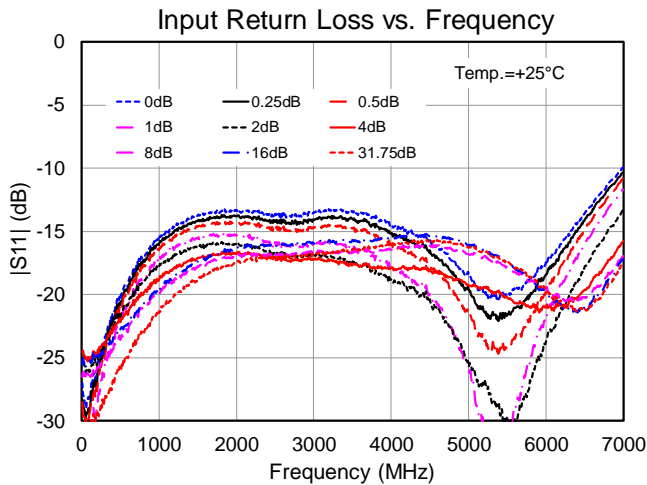
Evaluation Board Assembly Drawing
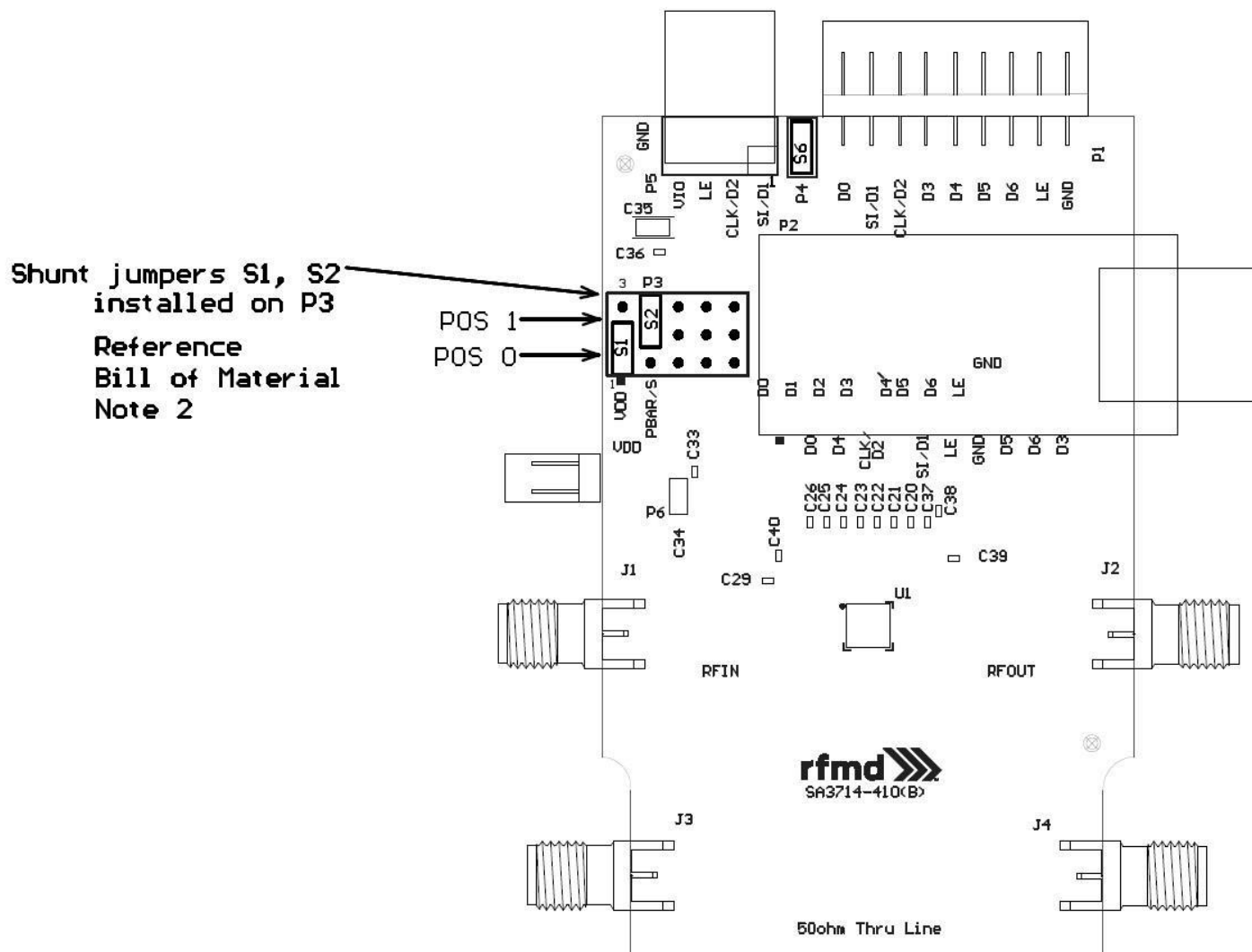
Evaluation Board Jumper Programming

Jumpers	Connector	Signal	Position	U1 Connection	Comment
S1	P3	Logic Voltage	**0**	VDD (from P6)	
			1	VIO (from P5)	
S2		PBar/S	**0**	GND	Parallel Mode
			1	U1_VDD	Serial Mode
S6	P4	LE	**OPEN**	LE	All Other Modes
			Installed	LE (from P5 Pin 3)	Serial Mode Using P5

Notes:
1. Default jumper settings are **BOLD**.

Evaluation Board Programming with USB Interface

Serial Mode
All programming jumpers on the evaluation board are set to the default values indicated in the table. Refer to the Control Bit Generator (CBG) Software Reference Manual for detailed instructions on how to setup the software for use. Apply the supply voltage to P6. Select 'RFSA3714' from the RFMD parts list of the CBG user interface. Set the attenuation value using the CBG user interface. The attenuator is set to the desired state and measurement can be taken.

Latched Parallel Mode
Evaluation board programming jumper S2 is set to '0'. All other programming jumpers are not required and can be set to any position. Refer to the Control Bit Generator Software Reference Manual for detailed instructions on how to set up the software for use. Apply the supply voltage to P6. Select 'RFSA3714-P' from the RFMD part list of the CBG user interface. Set the attenuation value using the CBG user interface. The attenuator is set to the desired state and measurements can be taken.

Evaluation Board Programming with External Bus

Serial Mode
The configuration allows the user to control the attenuator through the P5 connector using an external harness. Remove the USB interface board if it is currently installed on the evaluation board. Connect a user-supplied harness to the P5 connector. Note that the top row of P5 contains the serial bus signals and the bottom row is ground. Programming jumper S1 is set to '0' and S2 is set to '1'. Jumper S6 is installed and allows the LE signal to be routed from the P5 connector to the attenuator. Apply the supply voltage P6. Send the appropriate signals onto the serial bus lines in accordance with the Serial Mode Timing Diagram. The attenuator is set to the desired state and measurements can be taken.

Latched Parallel Mode
This configuration allows the user to control the attenuator through the P1 connector using an external harness. Remove the USB interface it if is currently installed on the evaluation board. Connect a user-supplied harness to the P1 connector. The parallel bus signal names for P1 are indicated on the evaluation board. Programming jumper S2 is set to '0' to select parallel mode. All other programming jumpers are not required and can be set to any position. Apply the supply voltage to P6. Send the appropriate signals onto the parallel bus lines in accordance with the Latched Parallel Mode Timing Diagram. The attenuator is set to the desired state and measurements can be taken.

Direct Parallel Mode
This configuration allows the user to control the attenuator through the P1 connector using an external harness. When using this mode the LE signal is held at logic high so that the attenuation will change immediately when there is a change in logic state for any of the parallel bus signals. Remove the USB interface if it is currently installed on the evaluation board. Connect a user-supplied harness to the P1 connector. The parallel bus signal names for P1 are indicated on the evaluation board. Programming jumper S2 is set to '0' to select parallel mode. All other programming jumpers are not required and can be set to any position. Apply the supply voltage to P6. Send the appropriate signals onto the parallel bus lines. The attenuator is set to the desired state and measurements can be taken.

Default Power-up State

The default attenuation state is maximum (31.75dB) when supply voltage is applied to the attenuator in both serial and parallel modes. If a different attenuation state is desired during power up, this can be accomplished by applying signals according to the Parallel Mode Truth Table. The attenuator will power up to the state applied to the parallel bus during turn on. The LE signal must be held to logic '0' during power up.

Pin Configuration and Description

Pad No.	Label	Description
1	C0.25	0.25dB Parallel Control Bit
2	VDD	Supply Voltage
3	PBAR/S	Mode Select Pin Logic Low = Parallel Logic High = Serial
4	GND	Ground Pin
5	RFIN	RF Input Pin, Incident RF power must enter this pin for rated thermal performance and reliability. Do not apply DC power to this pin. Pin may be DC grounded externally and is grounded thru resistors internal to the part.
6	GND	Ground Pin
7	GND	Ground Pin
8	GND	Ground Pin
9	GND	Ground Pin
10	GND	Ground Pin
11	GND	Ground Pin
12	GND	Ground Pin
13	GND	Ground Pin
14	RFOUT	RF Output Pin; Do not apply DC power to this pin. Pin may be DC grounded externally and is grounded thru resistors internal to the part.
15	GND	Ground Pin
16	LE	Latch Enable, the leading edge of signal on LE causes the attenuator to change setting for serial and latched parallel modes. For direct parallel mode keep LE at a logic high level.
17	CLK	Serial Clock Input
18	SI	Serial Data Input
19	C16	16dB Parallel Control Bit
20	C8	8dB Parallel Control Bit
21	C4	4dB Parallel Control Bit
22	C2	2dB Parallel Control Bit
23	C1	1dB Parallel Control Bit
24	C0.5	0.5dB Parallel Control Bit

Serial Mode Attenuation Word Truth Table

Attenuation Word								Attenuation State
D7	D6	D5	D4	D3	D2	D1	D0 (LSB)	
X	L	L	L	L	L	L	L	0dB / Reference Insertion Loss
X	L	L	L	L	L	L	H	0.25dB
X	L	L	L	L	L	H	L	0.5dB
X	L	L	L	L	H	L	L	1dB
X	L	L	L	H	L	L	L	2dB
X	L	L	H	L	L	L	L	4dB
X	L	H	L	L	L	L	L	8dB
X	H	L	L	L	L	L	L	16dB
X	H	H	H	H	H	H	H	31.75dB

Serial Mode Timing Diagram
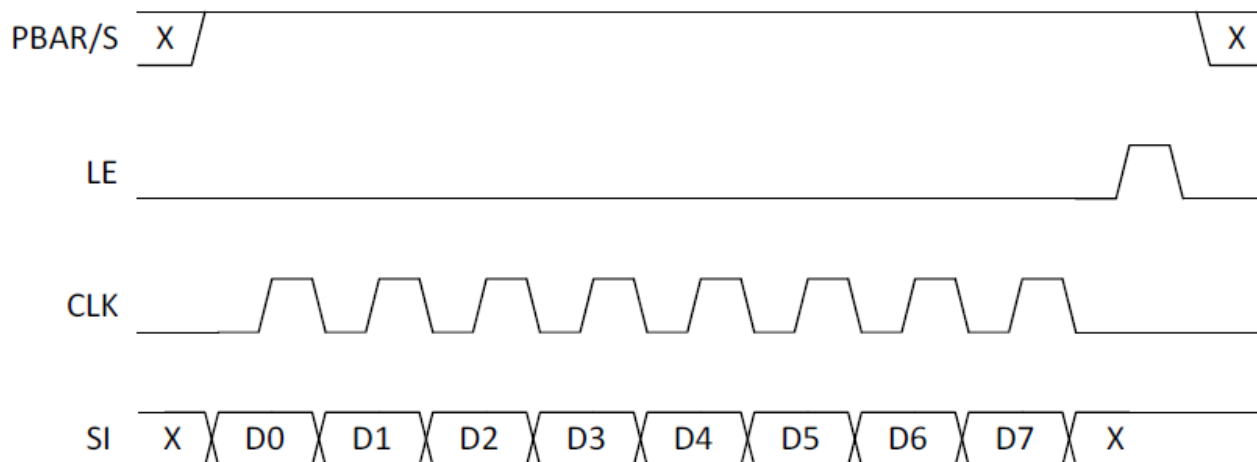
Note: Bit D7 is not used and can be set to logic high or low

Parallel Mode Truth Table

Parallel Input Control Setting							Attenuation State
D6 (C16)	D5 (C8)	D4 (C4)	D3 (C2)	D2 (C1)	D1 (C0.5)	D0 (C0.25)	
L	L	L	L	L	L	L	0dB / Reference Insertion Loss
L	L	L	L	L	L	H	0.25dB
L	L	L	L	L	H	L	0.5dB
L	L	L	L	H	L	L	1dB
L	L	L	H	L	L	L	2dB
L	L	H	L	L	L	L	4dB
L	H	L	L	L	L	L	8dB
H	L	L	L	L	L	L	16dB
H	H	H	H	H	H	H	31.75dB

Latched Parallel Mode Timing Diagram
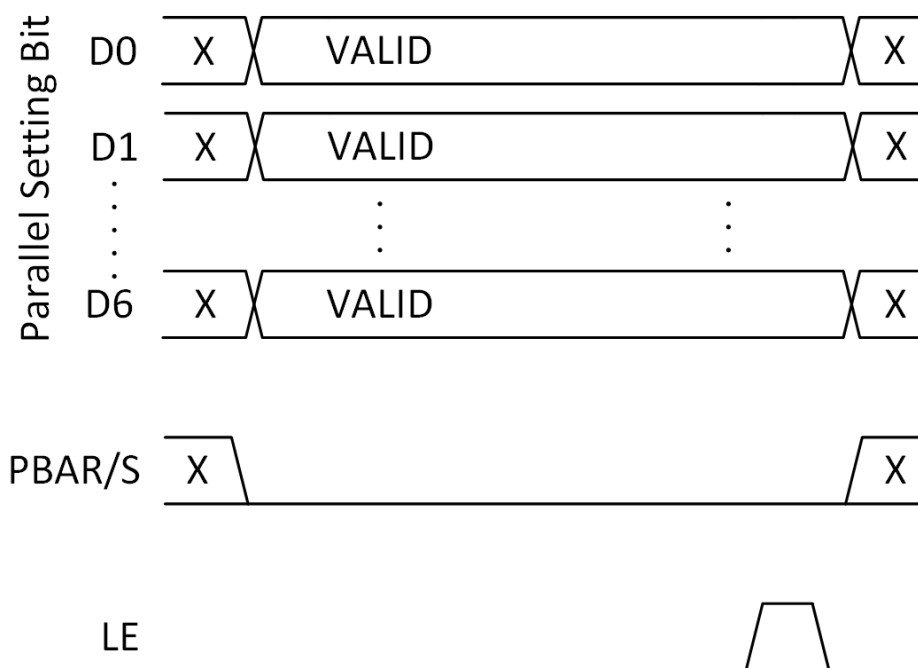
Serial Bus Timing Specification Diagram
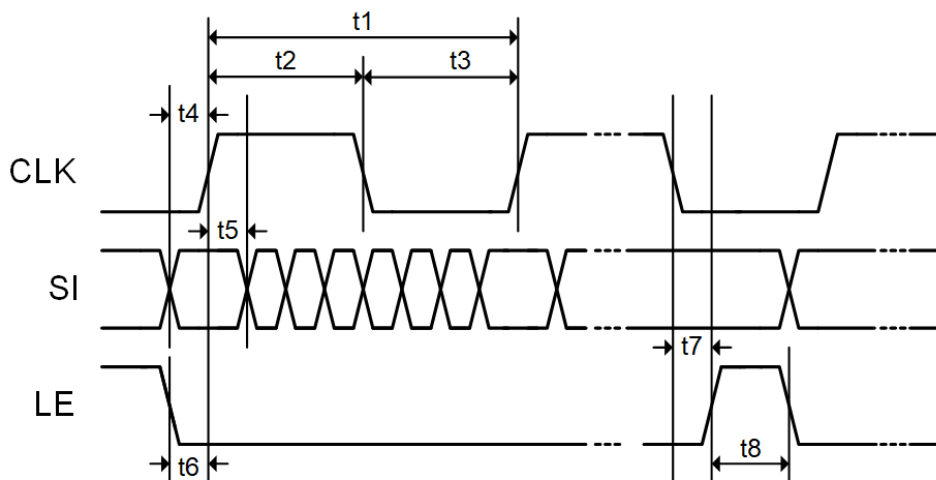
Serial Bus Timing Specifications

Parameter	Symbol	Min.	Max.	Unit
CLK Frequency	1/t1		25	MHz
CLK High Time	t2	20		ns
CLK Low Time	t3	20		ns
SI Setup Time	t4	5		ns
SI Hold Time	t5	5		ns
LE Low Setup Time	t6	5		ns
LE High Setup Time	t7	5		ns
LE High Time	t8	10		ns

Package Outline Drawing (Dimensions in millimeters)

TOP VIEW

BOTTOM VIEW

SIDE VIEW

Branding Diagram

SA3714
Trace Code
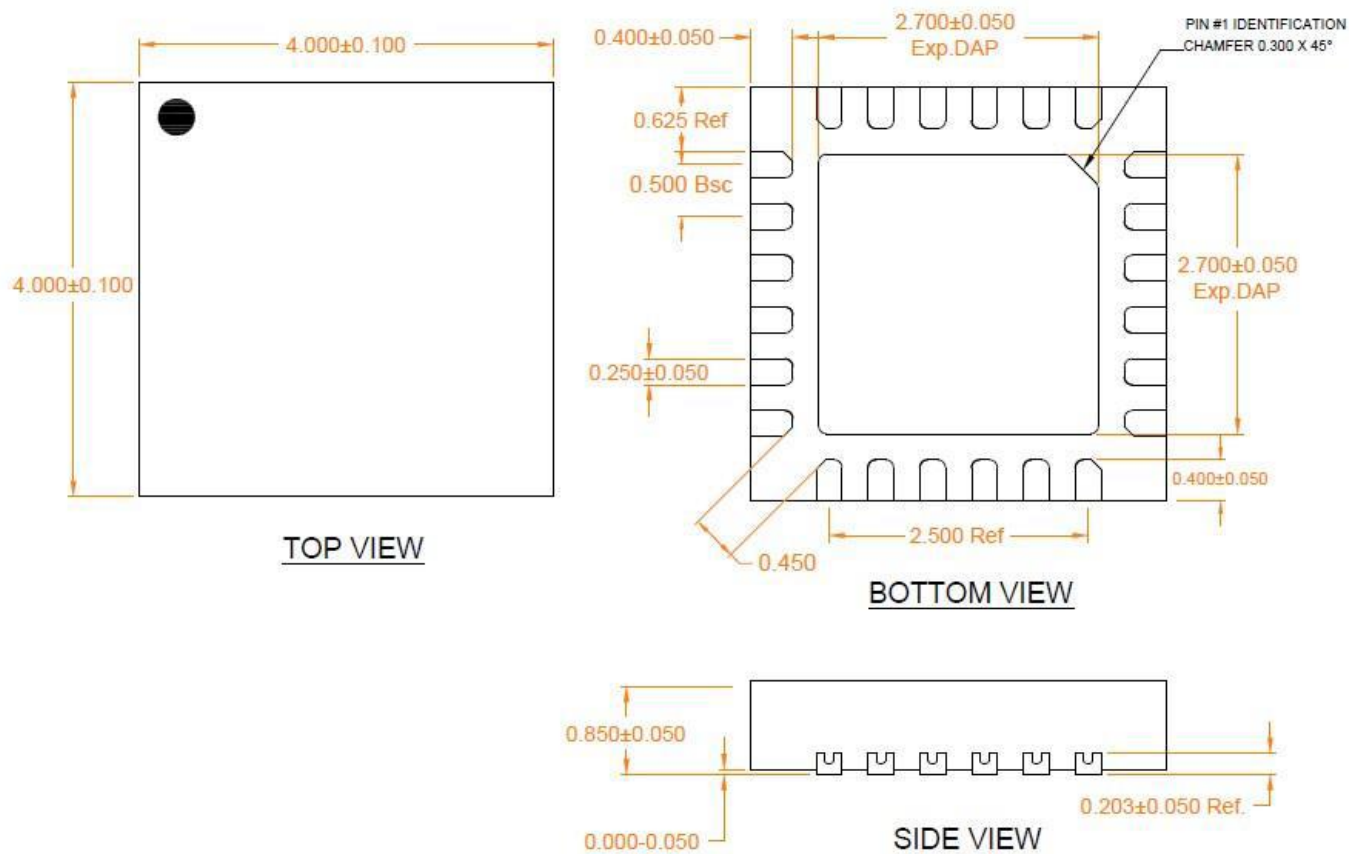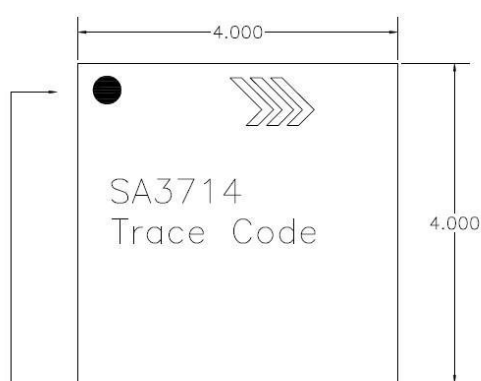
Pin 1 Indicator

Trace Code to be assigned by SubCon

Tape and Reel Information – Carrier and Cover Tape Dimensions

User Direction of Feed

$A_0 = 4.38mm$ [0.172]
$B_0 = 4.38mm$ [0.172]
$K_0 = 1.80mm$ [0.071]

NOTES:
1. ALL DIMENSIONS ARE MILLIMETERS [INCHES]
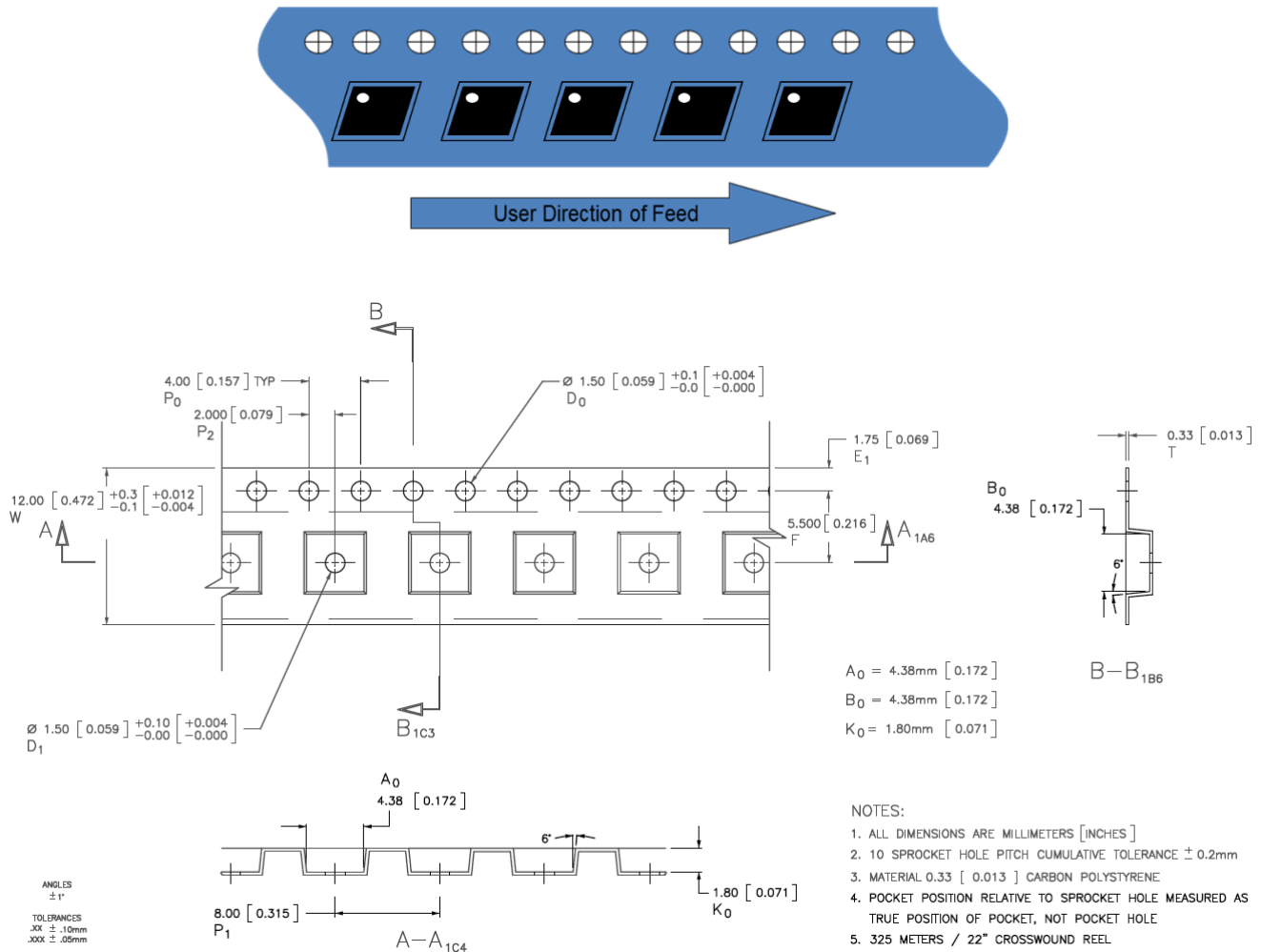2. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ± 0.2mm
3. MATERIAL 0.33 [0.013] CARBON POLYSTYRENE
4. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE
5. 325 METERS / 22" CROSSWOUND REEL

| Feature	Measure	Symbol	Size (in)	Size (mm)
Cavity	Length	A0	0.172	4.38
	Width	B0	0.172	4.38
	Depth	K0	0.071	1.80
	Pitch	P1	0.315	8.00
Centerline Distance	Cavity to Perforation - Length Direction	P2	0.079	2.00
	Cavity to Perforation - Width Direction	F	0.217	5.50
Cover Tape	Width	C	0.362	9.20
Carrier Tape	Width	W	0.472	12.0

Tape and Reel Information – Reel Dimensions

Standard T/R size = 2,500 pieces on a 13" reel.
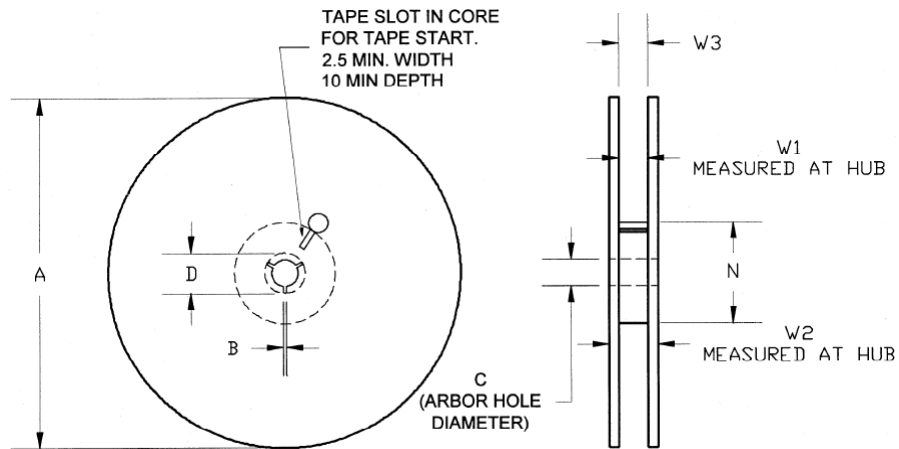
Feature	Measure	Symbol	Size (in)	Size (mm)
Flange	Diameter	A	12.992	330.0
	Thickness	W2	0.717	18.2
	Space Between Flange	W1	0.504	12.8
Hub	Outer Diameter	N	4.016	102.0
	Arbor Hole Diameter	C	0.512	13.0
	Key Slit Width	B	0.079	2.0
	Key Slit Diameter	D	0.787	20.0

Tape and Reel Information – Tape Length and Label Placement
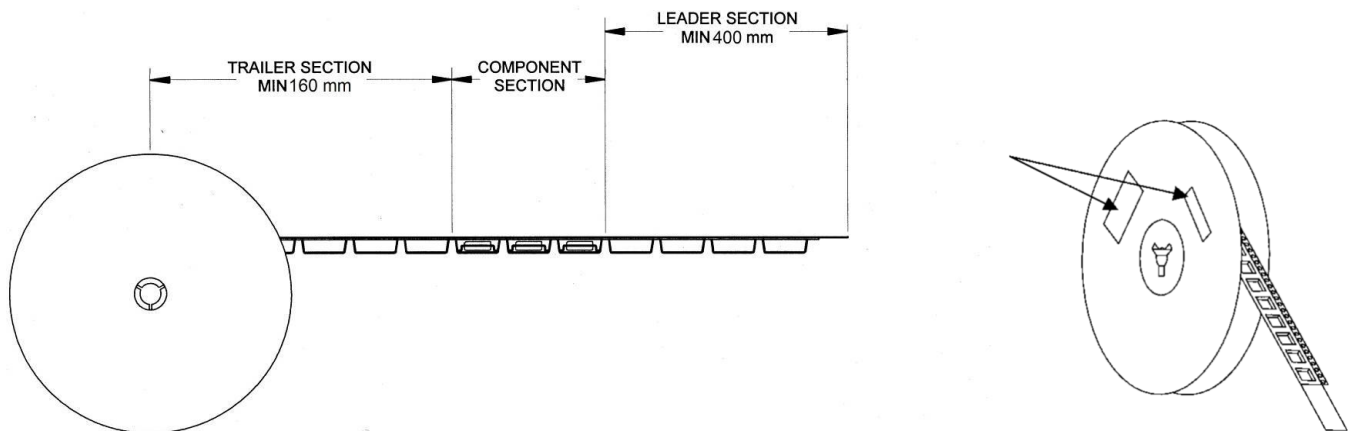
Notes:
1. Empty part cavities at the trailing and leading ends are sealed with cover tape. See EIA 481-1-A.
2. Labels are placed on the flange opposite the sprockets in the carrier tape.

Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1C	ESDA / JEDEC JS-001-2012
ESD – Charged Device Model (CDM)	Class C3	JEDEC JESD22-C101F
MSL – Moisture Sensitivity Level	Level 1	IPC/JEDEC J-STD-020

Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes.

Solder profiles available upon request.

Contact plating: NiPdAu *(Plating thickness: Ni 0.5~2.0066µm; Pd 0.01999~0.15011 µm; Au 0.00254~0.01501µm)*

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C15H12Br402) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Tel: 1-844-890-8163

Web: www.qorvo.com

Email: customer.support@qorvo.com

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